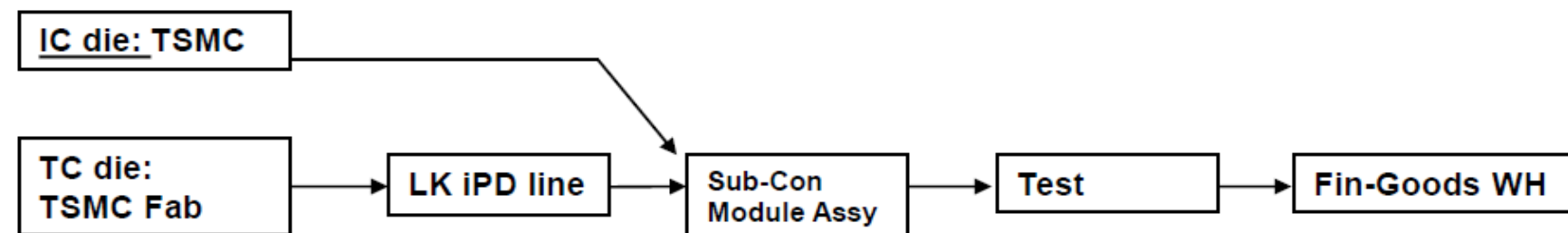


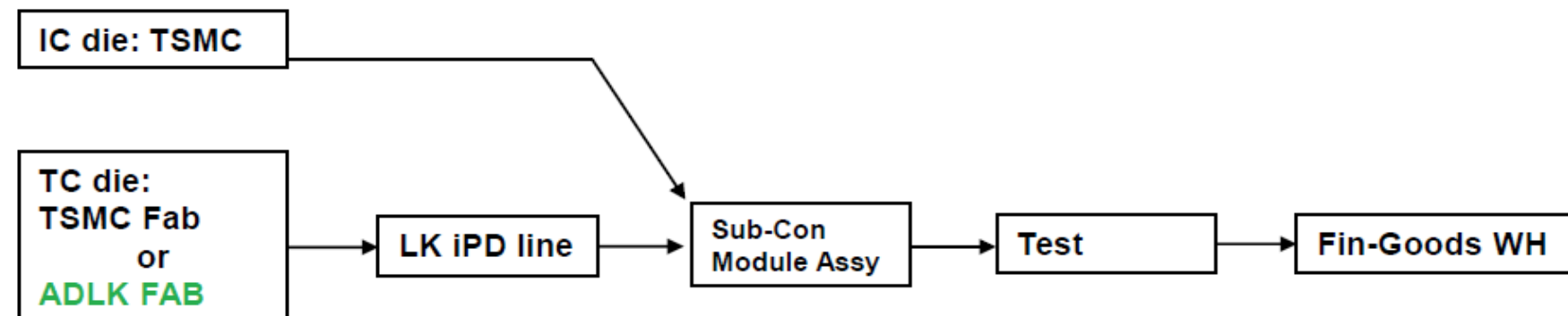
PCN 13_0109:

Alternate fab source for ISO TC start silicon die.
To enable additional wafer fabrication capacity.

Current Flow:



Alternate Flow:



QUALIFICATION RESULTS # 10558

TEST	SPECIFICATION	SAMPLE SIZE	Results
High Temperature Operating Life (HTOL)*	JEDEC <i>JESD22-A108</i>	1*77	Pass
Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A110</i>	1*77	Pass
Autoclave	JEDEC <i>JESD22-A102</i>	1*77	Pass
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	1*77	Pass
Early Life Failure (ELF)	MIL-STD-883 <i>Method 1015</i>	3*667	Pass
High Temperature Storage Life (HTSL)	JEDEC <i>JESD22-A103</i>	1*45	Pass
Solder Heat Resistance (SHR)*	<i>ADI-0049</i>	1*30	Pass
Latch-Up	JEDEC <i>JESD78</i>	6	ADUM1201 Pass 200mA ADUM1250 Pass 100mA ADUM3100 Pass 200mA
Electrostatic Discharge <i>Human Body Model</i>	ESDA/JEDEC <i>JDS-001-2011</i>	3/voltage	ADUM1201 Pass 3500V ADUM1250 Pass 4000V ADUM3100 Pass 1500V
Electrostatic Discharge <i>Field-Induced Charged Device Model</i>	JEDEC <i>JESD22-C101</i>	3/voltage	ADUM1201 Pass 1000V ADUM1250 Pass 1250V ADUM3100 Pass 750V
Electrostatic Discharge <i>Machine Model</i>	JEDEC <i>JESD22-A115</i>	3/voltage	ADUM1201 Pass 100V ADUM1250 Pass 400V ADUM3100 Pass 400V

*Preconditioned per JEDEC/IPC J-STD-020